Title: CHEMICAL VAPOR DEPOSITION OF TITANIUM

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(New) The via of claim \$1, further including a titanium nitride layer interposed between the second layer and the fill.

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I I (New) The via of claim 8, wherein the first layer is coupled to a sidewall of the contact opening.

(New) The via of claim 7, wherein the first layer is coupled to a high aspect ratio contact opening.

REMARKS

Currently claims 51-56 and 60-85 are pending in the application. The Applicant respectfully requests that the preliminary amendment described herein be entered into the record prior to examination and consideration of the above-identified application. The Examiner is invited to contact Applicant's Representatives at the below-listed telephone number if there are any questions regarding this Preliminary Amendment or if prosecution of this application may be assisted thereby.

Respectfully submitted,

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By their Representatives,

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This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

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CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

CHEMICAL VAPOR DEPOSITION OF TITANIUM Applicant: Gurtej Singh Sandhu et al.

The paragraph beginning on page 1, line 4.

This application is a Divisional of U.S. Application No. 09/489,187, filed on January 20, 2000, which is a continuation-in-part of U.S. Application Serial No. 09/030,705, filed February 25, 1998, now issued as U.S. Patent 6,143,362 on November 7, 2000, which is hereby incorporated by reference in its entirety.

